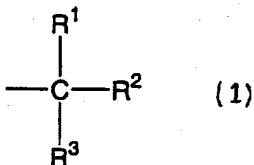


Scope of Claims

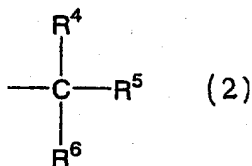
1. A positive-working radiation-sensitive composition which
4 is characterized in that it is a positive-working radiation-
sensitive composition containing a) a compound with an
alkali-soluble group protected by an acid labile group a and
b) an acid generator which generates acid by irradiation with
8 radiation, and any of the following conditions a1) to a3) are
satisfied.

a1) The alkali-soluble group is a carboxyl group and the
12 acid labile group is represented by general formula (1)



(R¹ and R² are aromatic rings, and R³ represents an alkyl
group, a substituted alkyl group, a cycloalkyl group or an
16 aromatic ring; and R¹ to R³ may be the same or different.)

a2) The acid labile group is represented by general formula
(2)



(R⁴ to R⁶ are each an alkyl group, a substituted alkyl group,
a cycloalkyl group or an aromatic ring, and at least one of
R⁴ to R⁶ is an aromatic ring with an electron-donating group;
24 and R⁴ to R⁶ may be the same or different.)

a3) The acid labile group a has an alkali-soluble group or alternatively the acid labile group a has an alkali-soluble group protected by an acid labile group b.

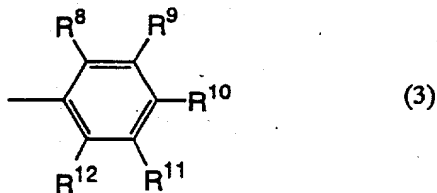
2. A positive-working radiation-sensitive composition according to Claim 1 where condition a1) is satisfied.

3. A positive-working radiation-sensitive composition according to Claim 2 which is characterized in that R¹ to R³ are each independently an aryl group or a substituted aryl group.

4. A positive-working radiation-sensitive composition according to Claim 1 where condition a2) is satisfied.

5. A positive-working radiation-sensitive composition according to Claim 4 which is characterized in that the alkali-soluble group in the compound meeting condition a2) is a carboxyl group or a phenolic hydroxy group.

6. A positive-working radiation-sensitive composition according to Claim 4 which is characterized in that the aromatic ring with an electron-donating group is of structure represented by general formula (3).



(R⁸, R¹⁰ and R¹² each independently represents a hydrogen atom, an alkyl group with 1 to 4 carbons or an alkoxy group with 1 to 6 carbons, and at least one of these represents such an alkyl group or alkoxy group. R⁹ and R¹¹ each independently

represents a hydrogen atom, an alkyl group with 1 to 4 carbons or an alkoxy group with 1 to 6 carbons.)

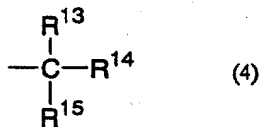
4 7. A positive-working radiation-sensitive composition according to Claim 4 where the electron-donating group is an alkoxy group with 1 to 6 carbons.

8 8. A positive-working radiation-sensitive composition according to Claim 1 where condition a3) is satisfied.

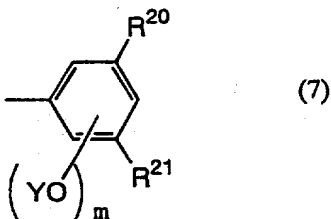
12 9. A positive-working radiation-sensitive composition according to Claim 8 which is characterized in that the acid labile group a in the compound meeting condition a3) has at least one phenolic hydroxyl group, or alternatively a phenolic hydroxyl group further protected with acid labile group b.

20 10. A positive-working radiation-sensitive composition according to Claim 8 which is characterized in that the acid labile group a in the compound meeting condition a3) has at least one carboxyl group or alternatively a carboxyl group further protected with acid labile group b.

24 11. A positive-working radiation-sensitive composition according to Claim 8 which is characterized in that the labile group a in the compound meeting condition a3) is a group represented by general formula (4).

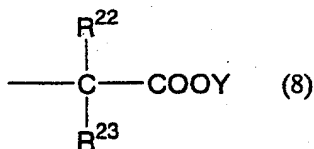


28 (R¹³ to R¹⁵ are each independently an alkyl group, a substituted alkyl group, a cycloalkyl group, an aryl group, a substituted aryl group, a group containing an alkali-soluble



(R²⁰ and R²¹ each independently represents a hydrogen atom or an alkyl group with 1 to 4 carbons. Y represents an acid labile group *b* or a hydrogen atom, and *m* is 1 to 3.)

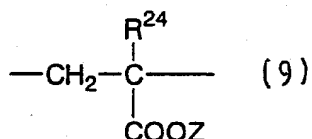
14. A positive-working radiation-sensitive composition according to Claim 11 which is characterized in that at least one of R¹³ to R¹⁵ of general formula (4) is of structure represented by general formula (8).



(R²² and R²³ represent a hydrogen atom or an alkyl group with 1 to 4 carbons. Y represents an acid labile group *b* or a hydrogen atom.)

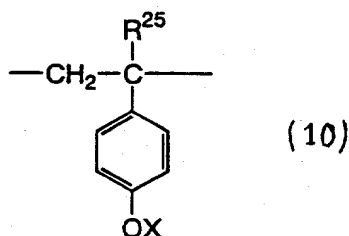
15. A positive-working radiation-sensitive composition according to Claim 1 which is characterized in that the compound meeting any of conditions a1) to a3) is a polymer of weight average molecular weight from 5,000 to 50,000.

16. A positive-working radiation-sensitive composition according to Claim 1 which is characterized in that the compound meeting any of conditions a1) to a3) is a polymer containing structural units represented by general formula (9).



4 (R²⁴ represents a hydrogen atom, an alkyl group with 1 to 4 carbons, a cyano group or a halogen. Z is a group represented by general formula (1), (2) or (4).

8 17. A positive-working radiation-sensitive composition according to Claim 4 or Claim 8 which is characterized in that the compound meeting condition a2) or a3) is a polymer containing structural units represented by general formula (10).



12 (R²³ represents a hydrogen atom, an alkyl group with 1 to 4 carbons, a cyano group or a halogen. X is an acid labile group represented by general formula (2) or (4).

16 18. A positive-working radiation-sensitive composition according to Claim 16 which is characterized in that R²⁴ is a cyano group or a halogen.

20 19. A method for the production of a pattern in which a positive-working radiation-sensitive composition according to Claim 1 is applied onto a substrate which is to undergo processing, and drying, exposure and development carried out.

24

20. A method of pattern production according to Claim 19 which is characterized in that the exposure is carried out by means of an electron beam.

4

an alkali-soluble group or acid labile group a has an alkali-soluble group protected by an acid labile group b.

5 With this constitution, it is possible by means of the present invention to obtain a positive-working radiation-sensitive composition of high sensitivity having a resolution which enables sub-quarter micron pattern processing to be carried out.